JJMICROELECTRONICS

±30V, 29A&-27A, 21mΩ&20mΩ N And P-channel Power Trench MOSFET

JMTG200C03D

Features

- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant

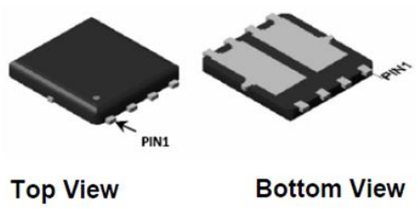
Applications

- Load Switch
- PWM Application
- Power Management

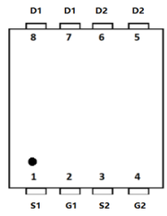
Product Summary

Parameters	N	P	Unit
V_{DSS}	30	-30	V
$V_{GS(th)\_Typ}$	1.7	-1.7	V
I_D(@V_{GS}=10V)	29	-27	A
$R_{DS(ON)\_Typ}$(@V_{GS}=10V	15	15	mΩ
$R_{DS(ON)\_Typ}$(@V_{GS}=4.5V	21	20	mΩ

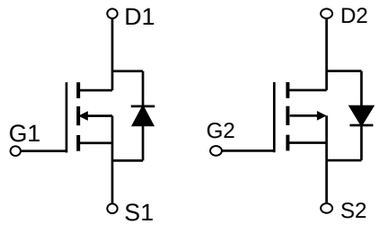
RoHS



PDFN5X6-8L-D



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTG200C03D	G200C03D	1	Tape&Reel	PDFN5x6-8L-D	5000	50000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter		Value-N	Value-P	Unit
V_{DS}	Drain-to-Source Voltage		30	-30	V
V_{GS}	Gate-to-Source Voltage		±20		V
I_D	Continuous Drain Current	T_C = 25°C	29	-27	A
		T_C = 100°C	18	-17	
I_{DM}	Pulsed Drain Current (1)		Refer to Fig.4		A
E_{AS}	Single Pulsed Avalanche Energy (2)		15	33	mJ
P_D	Power Dissipation	T_C = 25°C	24	24	W
		T_C = 100°C	10	10	
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150		°C

Thermal Characteristics

Symbol	Parameter	Max		Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient(3)	58	57	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	5.2	5.2	

Electrical Characteristics-N(T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 30V, V_{GS} = 0V	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1.2	1.7	2.2	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance(4)	V_{GS} = 10V, I_D = 5A	-	15	17	mΩ
		V_{GS} = 4.5V, I_D = 3A	-	21	28	mΩ
Dynamic Characteristics						
R_g	Gate Resistance	f = 1MHz	-	1.8	-	Ω
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = 15V, f = 1MHz	344	481	649	pF
C_{oss}	Output Capacitance		50	71	95	pF
C_{rss}	Reverse Transfer Capacitance		39	54	73	pF
Q_g	Total Gate Charge	V_{GS} = 0 to 10V V_{DS} = 15V, I_D = 5A	7	10	14	nC
Q_{gs}	Gate Source Charge		-	1.8	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	2.1	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	V_{GS} = 10V, V_{DD} = 15V I_D= 5A, R_{GEN} = 2.7Ω	-	5	-	ns
t_r	Turn-On Rise Time		-	28	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	15	-	ns
t_f	Turn-Off Fall Time		-	2	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	29	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	114	A
V_{SD}	Body Diode Forward Voltage	V_{GS} = 0V, I_S = 5A	-		1.2	V
trr	Body Diode Reverse Recovery Time	I_F = 5A, di/dt = 100A/us	-	7.7	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	2.3	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25C, V_{DD}=15V, V_{GS}=10V, R_G=25ohm, L=0.5mH, I_{AS}=7.7A, V_{DD}=0V during time in avalanche.
3. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
4. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Electrical Characteristics-P (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	I_D = -250μA, V_{GS} = 0V	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -30V, V_{GS} = 0V	-	-	-1.0	μA
I_{GSS}	Gate-Body Leakage Current	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250μA	-1.2	-1.7	-2.2	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance(5)	V_{GS} = -10V, I_D = -15A	-	15	21	mΩ
		V_{GS} = -4.5V, I_D = -10A	-	20	32	mΩ
Dynamic Characteristics						
R_g	Gate Resistance	f = 1MHz	-	12	-	Ω
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = -15V, f = 1MHz	921	1290	1741	pF
C_{oss}	Output Capacitance		120	169	228	pF
C_{rss}	Reverse Transfer Capacitance		94	131	177	pF
Q_g	Total Gate Charge	V_{GS} = 0 to -4.5V, V_{DS} = -10V, I_D = -3A	17	24	32	nC
Q_{gs}	Gate Source Charge		-	4	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	V_{GS} = -10V, V_{DD} = -15V, I_D= -3A, R_{GEN} = 3Ω	-	5	-	ns
t_r	Turn-On Rise Time		-	22	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	61	-	ns
t_f	Turn-Off Fall Time		-	55	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	-4	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	-14	A
V_{SD}	Body Diode Forward Voltage	V_{GS} = 0V, I_S = -3A	-		-1.2	V
trr	Body Diode Reverse Recovery Time	I_F = -20A, di/dt = -100A/us	9	12	17	ns
Qrr	Body Diode Reverse Recovery Charge		-	4.2	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25C, V_{DD}=-15V, V_{GS}=-10V, R_G=25ohm, L=0.5mH, I_{AS}=-11.48A, V_{DD}=0V during time in avalanche.
3. $R_{\theta JA}$ is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB.
4. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics-N

Figure 1: Power De-rating

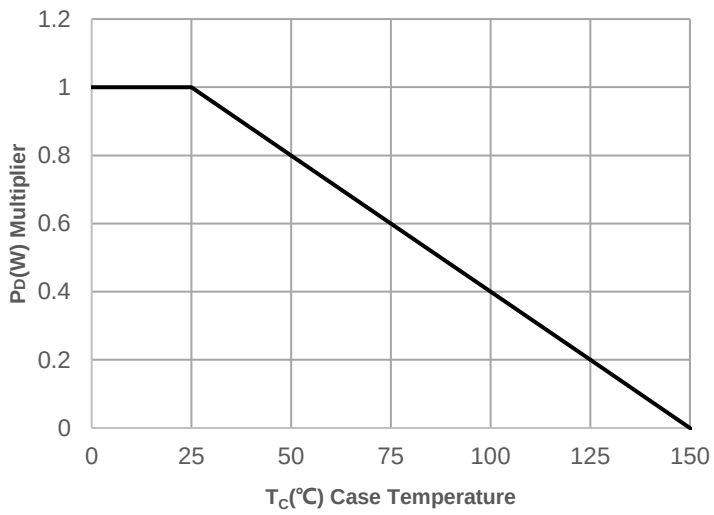


Figure 2: Current De-rating

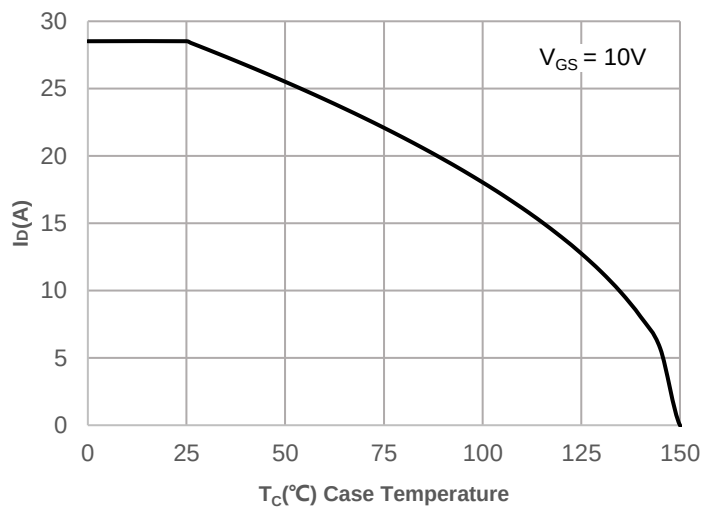


Figure 3: Normalized Maximum Transient Thermal Impedance

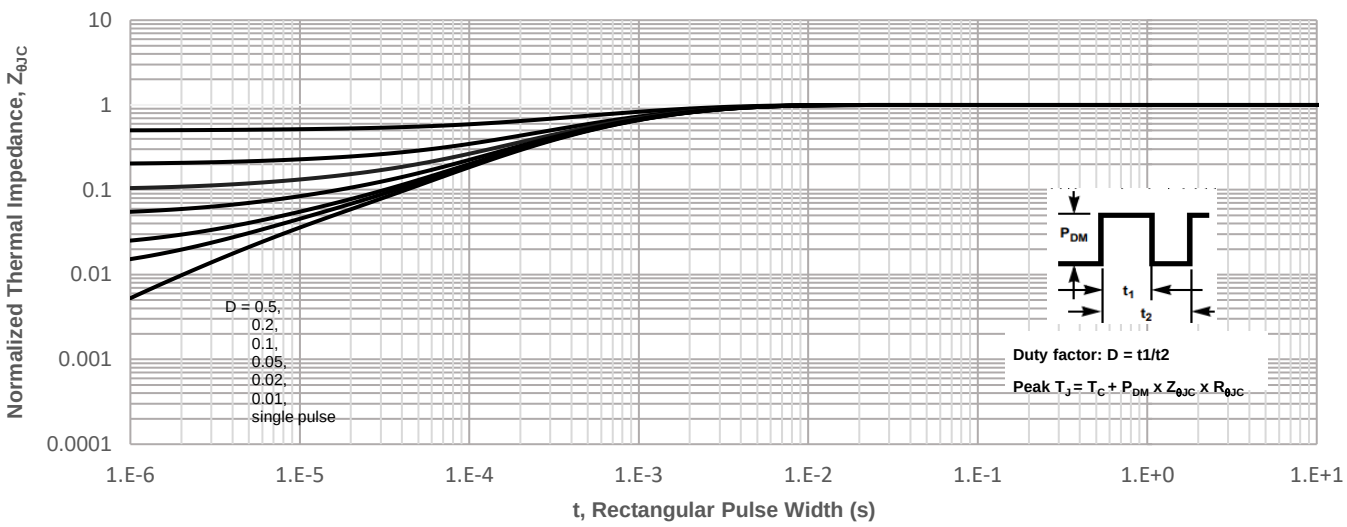
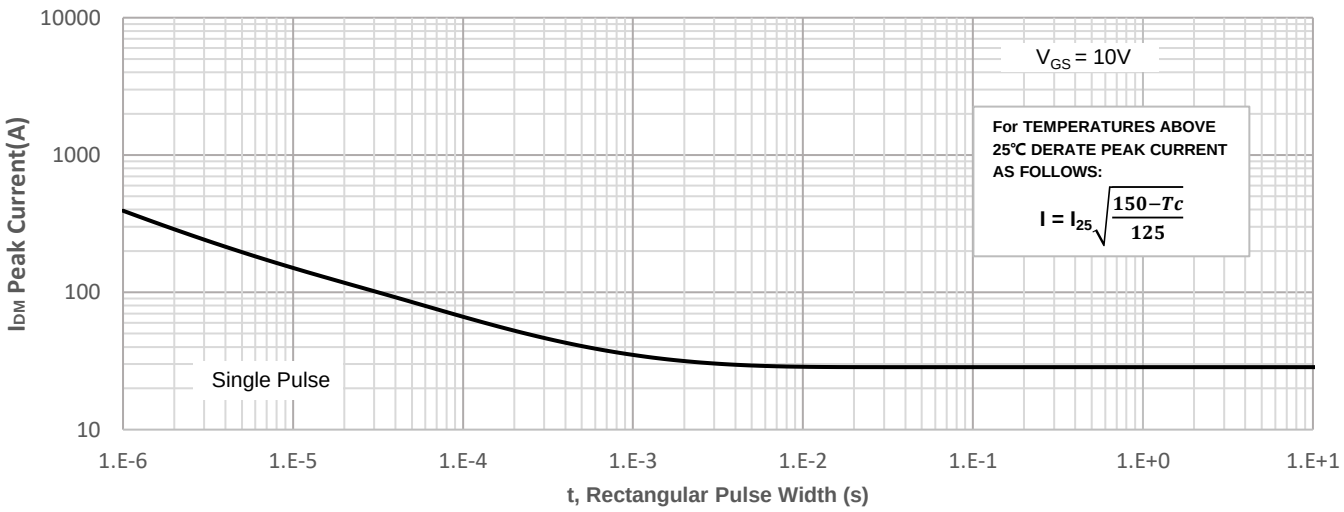


Figure 4: Peak Current Capacity



Typical Performance Characteristics-N

Figure 5: Output Characteristics

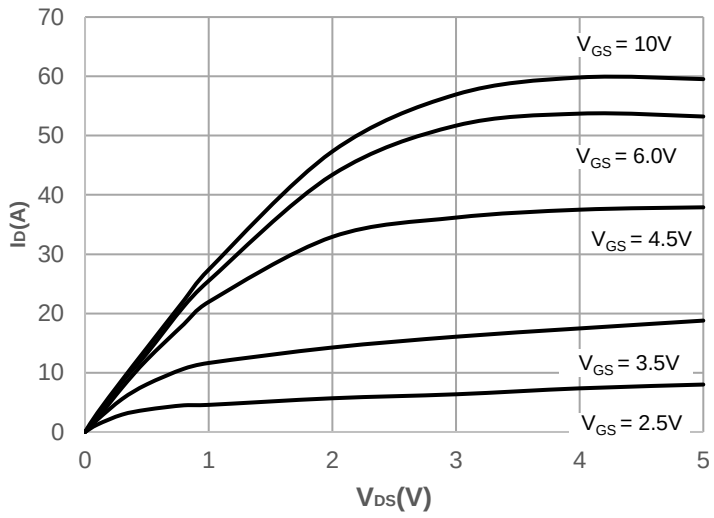


Figure 6: Typical Transfer Characteristics

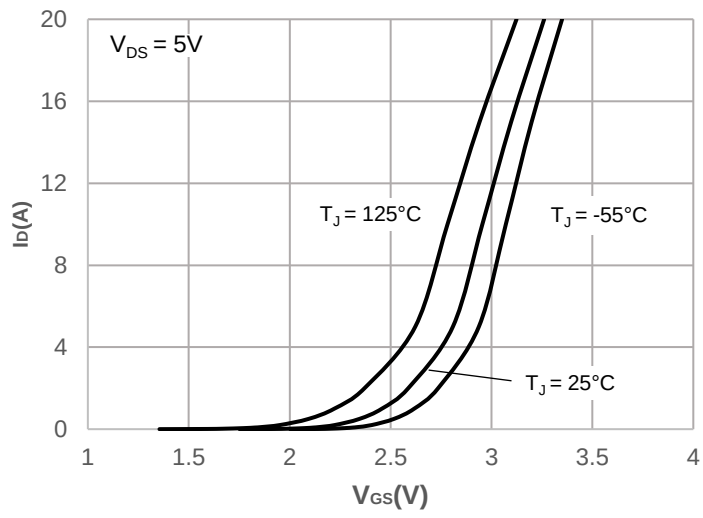


Figure 7: On-resistance vs. Drain Current

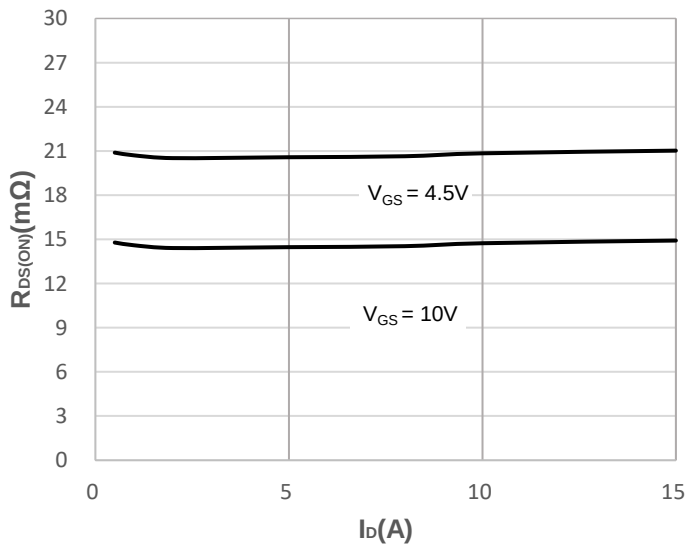


Figure 8: Body Diode Characteristics

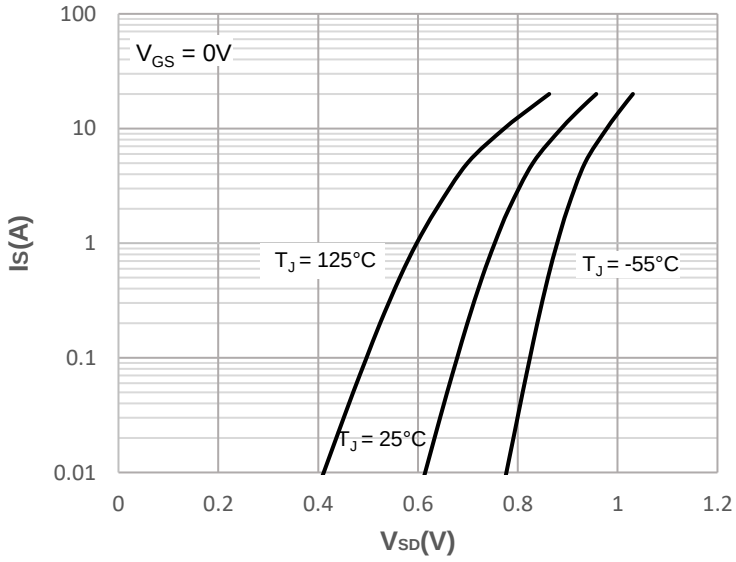


Figure 9: Gate Charge Characteristics

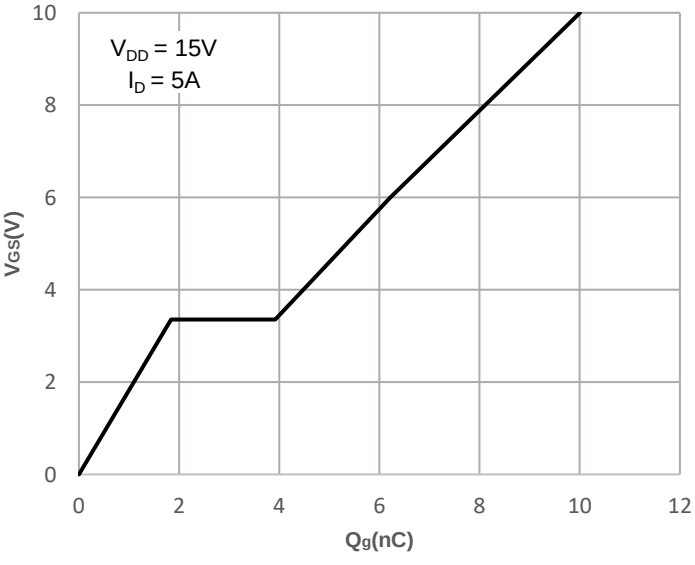
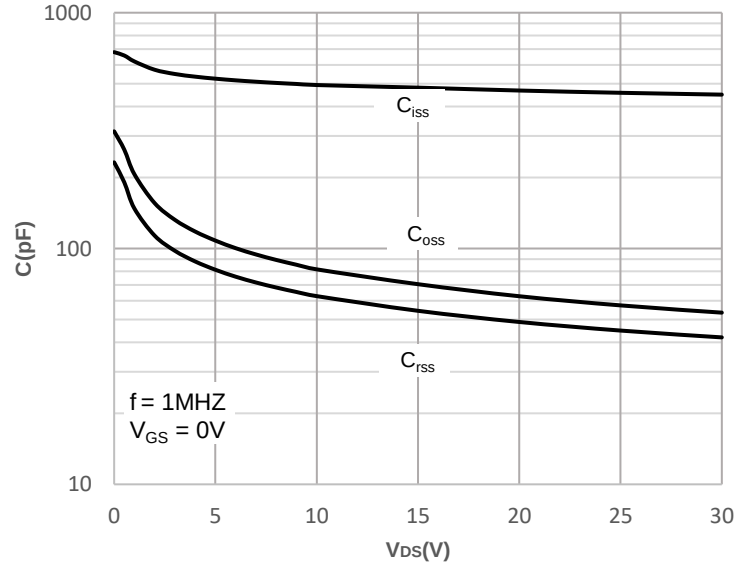


Figure 10: Capacitance Characteristics



Typical Performance Characteristics-N

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

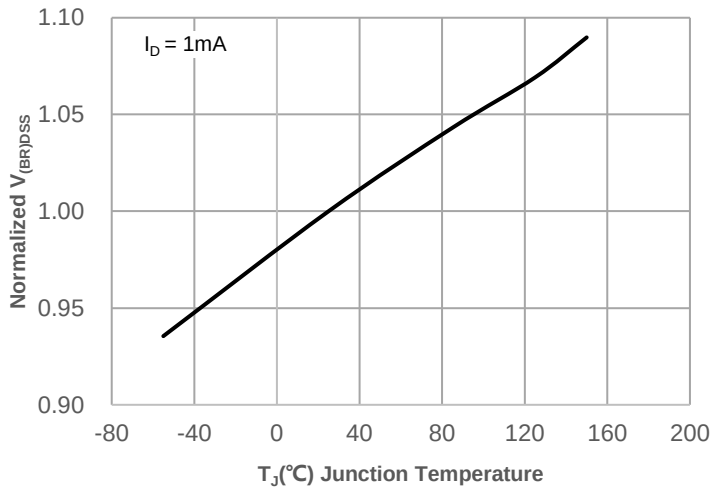


Figure 12: Normalized on Resistance vs. Junction Temperature

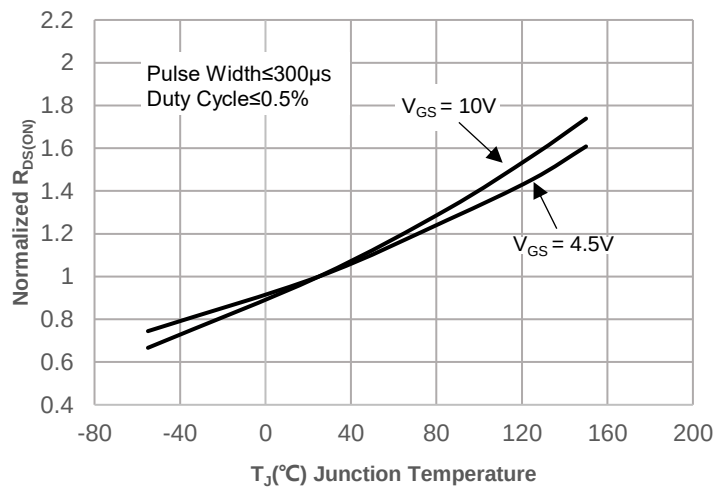


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

Figure 14: $R_{DS(ON)}$ vs. V_{GS}

Figure 15: Maximum Safe Operating Area

Typical Performance Characteristics-P

Figure 1: Power De-rating

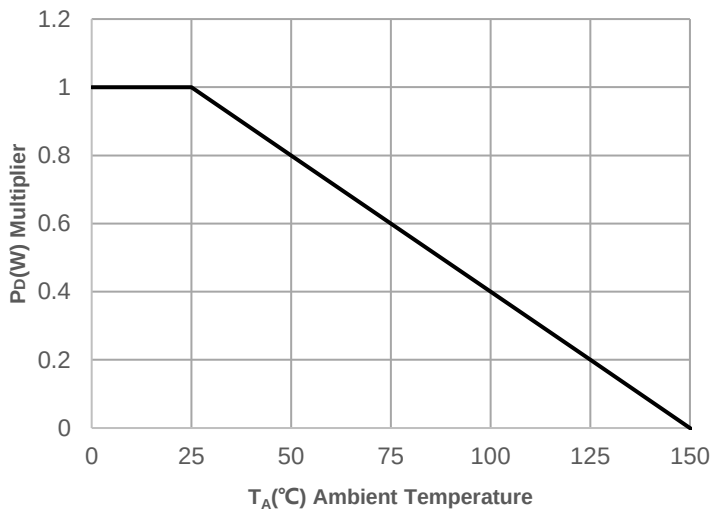


Figure 2: Current De-rating

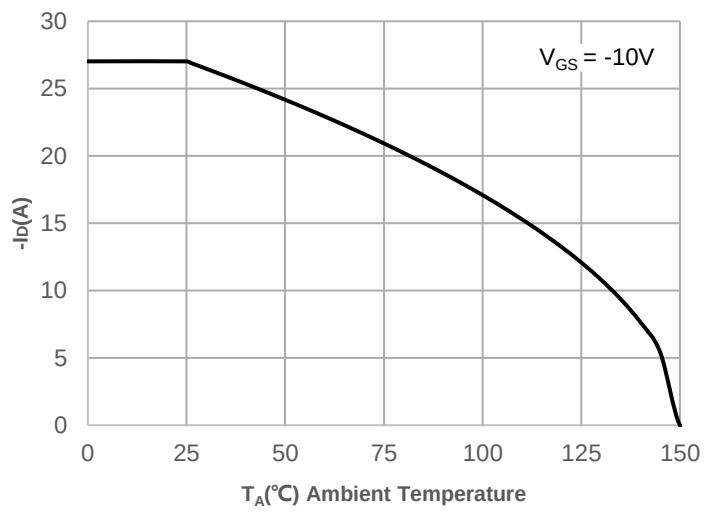


Figure 3: Normalized Maximum Transient Thermal Impedance

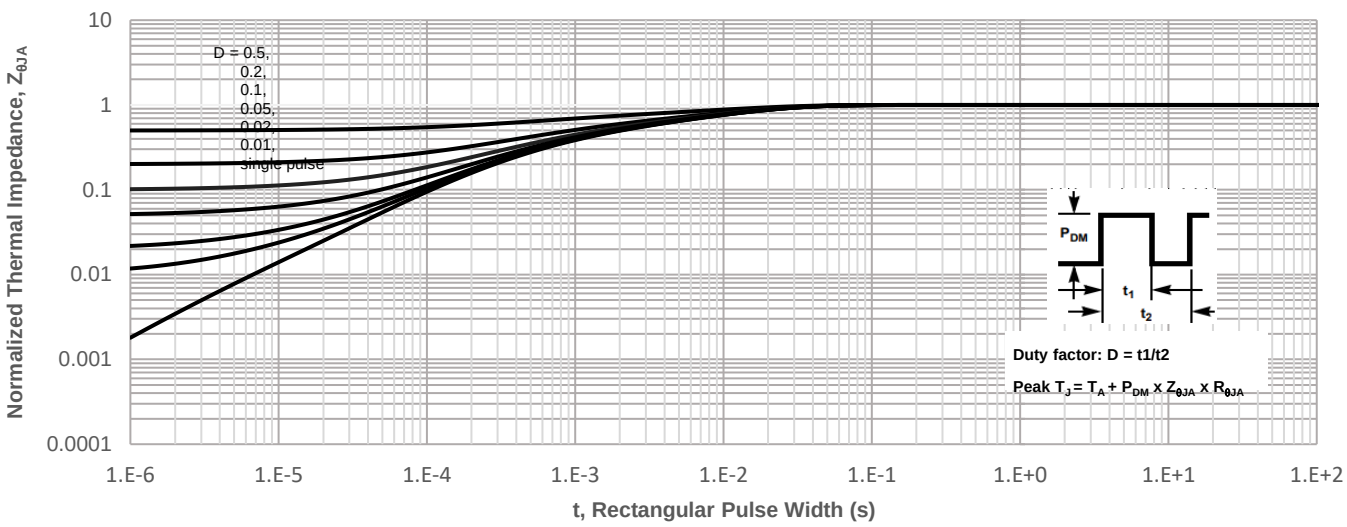
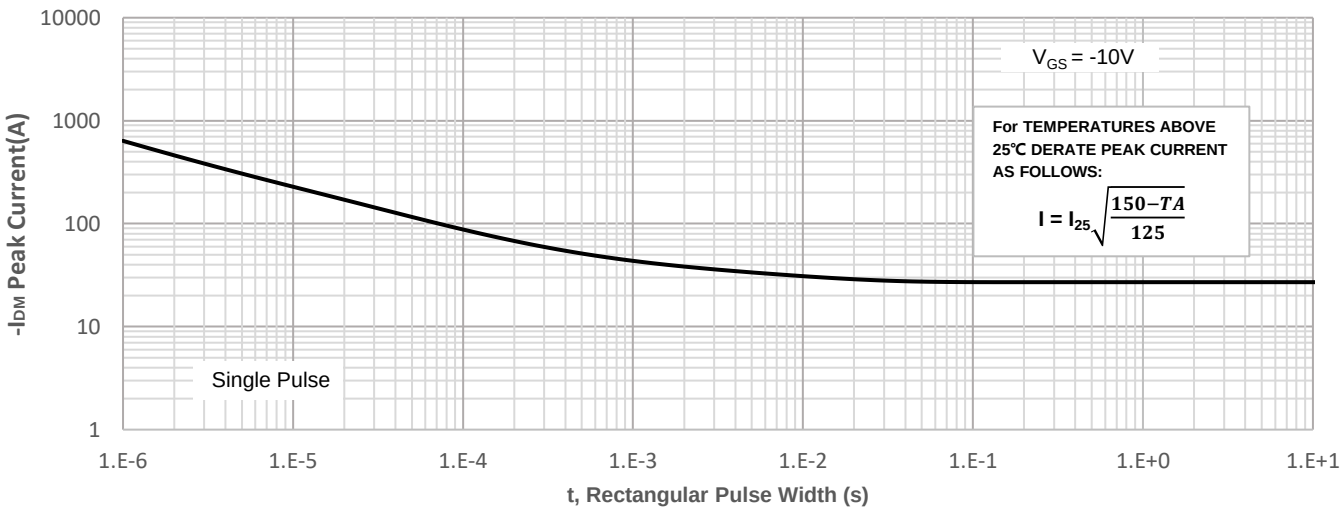


Figure 4: Peak Current Capacity



Typical Performance Characteristics-P

Figure 5: Output Characteristics

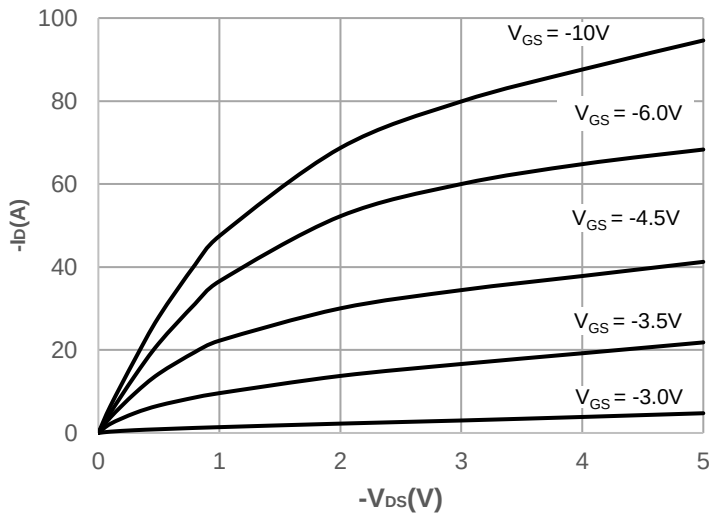


Figure 6: Typical Transfer Characteristics

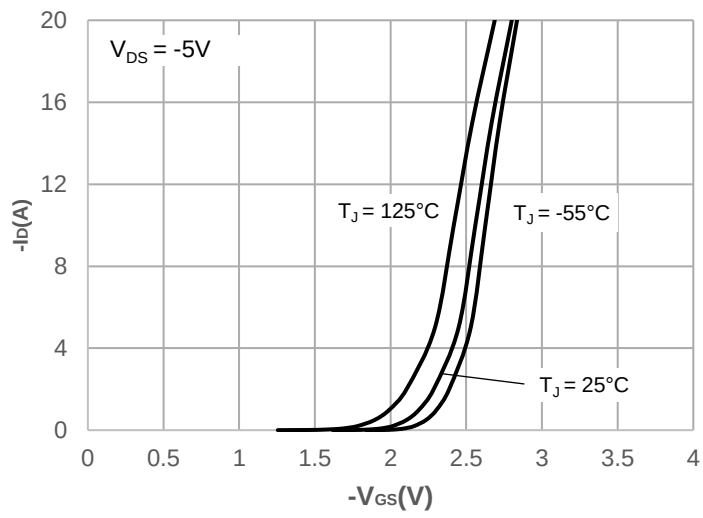


Figure 7: On-resistance vs. Drain Current

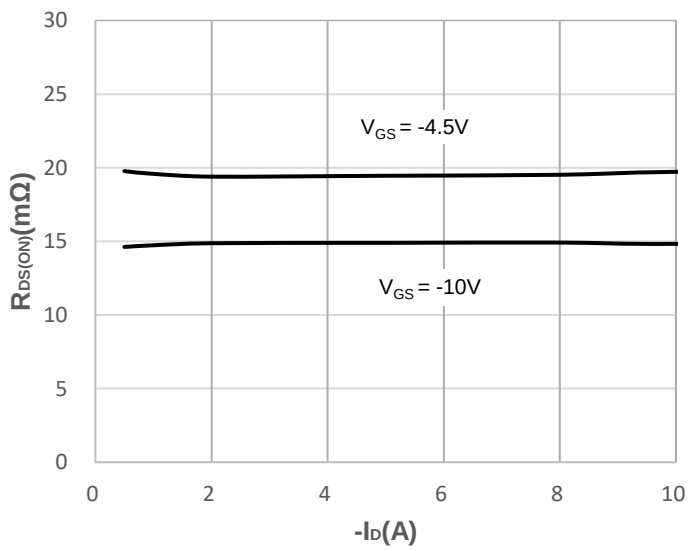


Figure 8: Body Diode Characteristics

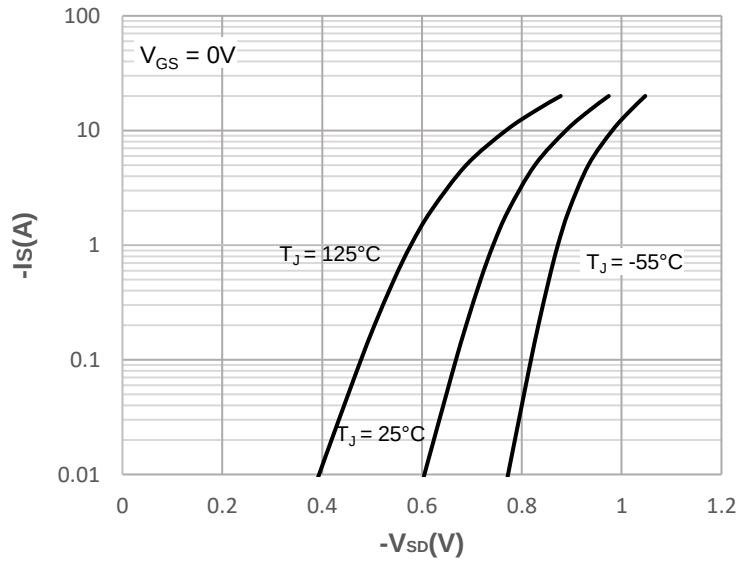


Figure 9: Gate Charge Characteristics

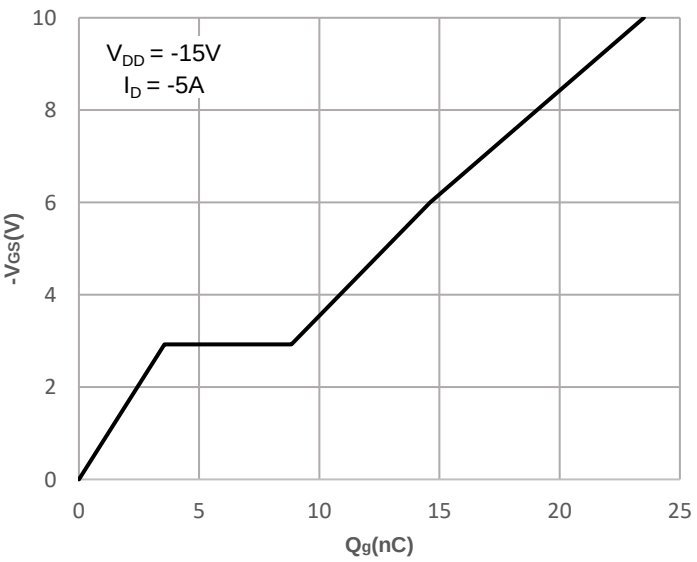
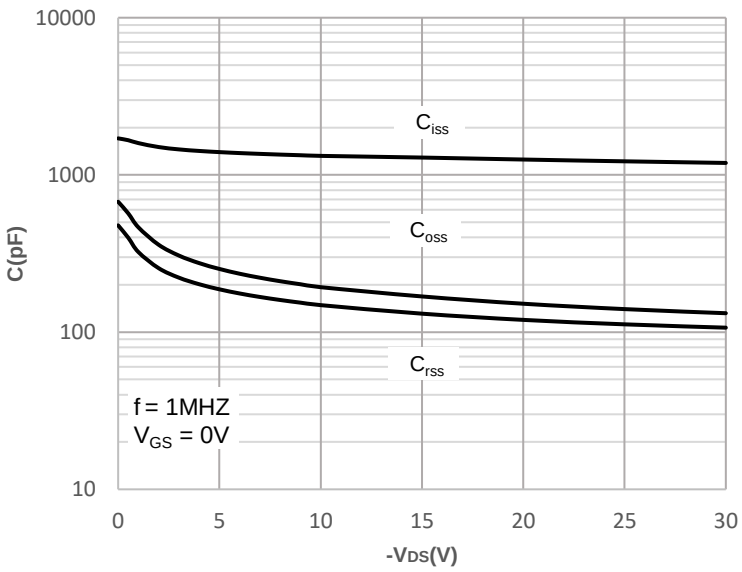


Figure 10: Capacitance Characteristics



Typical Performance Characteristics-P

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

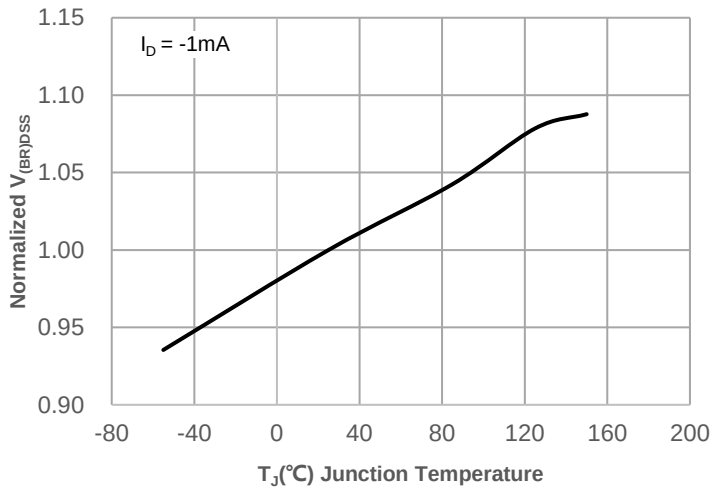


Figure 12: Normalized on Resistance vs. Junction Temperature

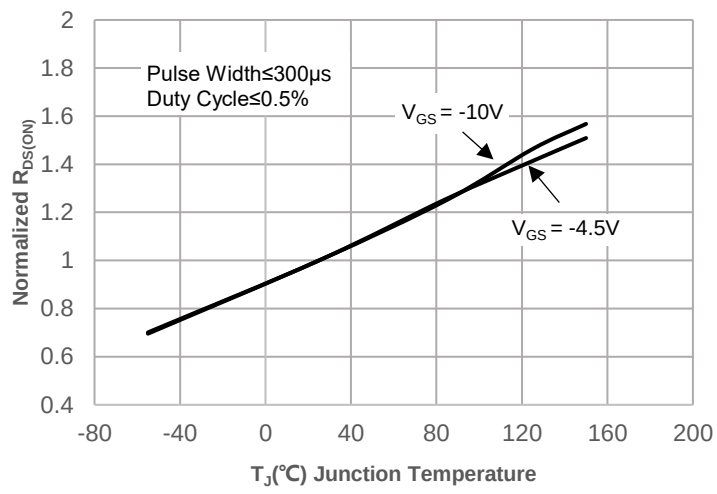


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

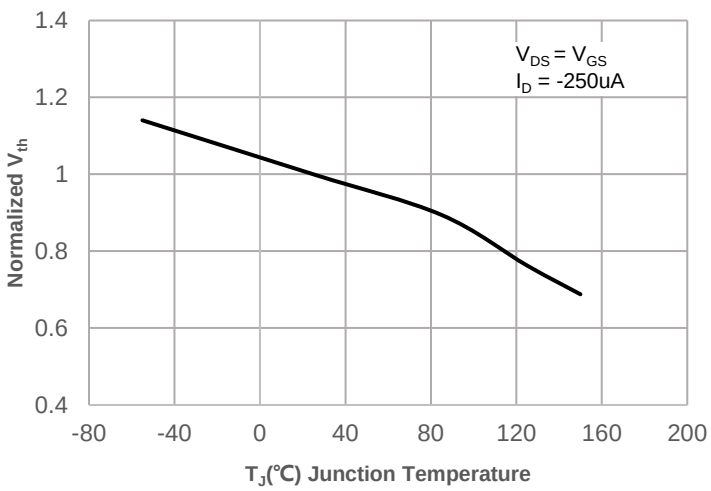


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

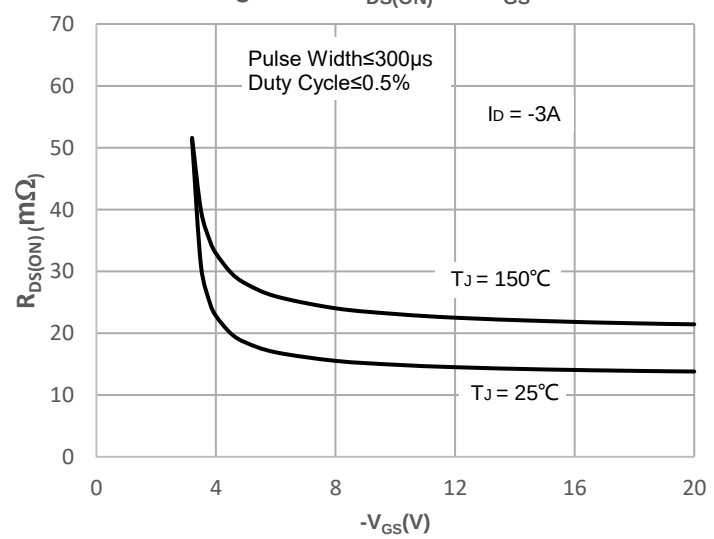
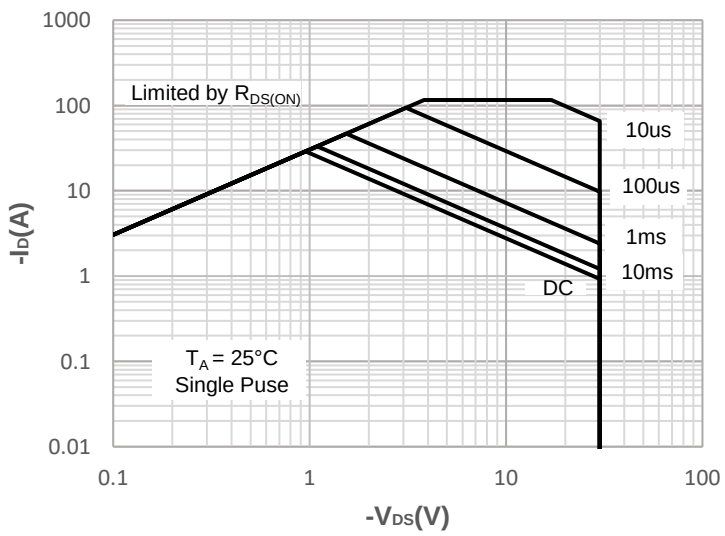


Figure 15: Maximum Safe Operating Area



Test Circuit

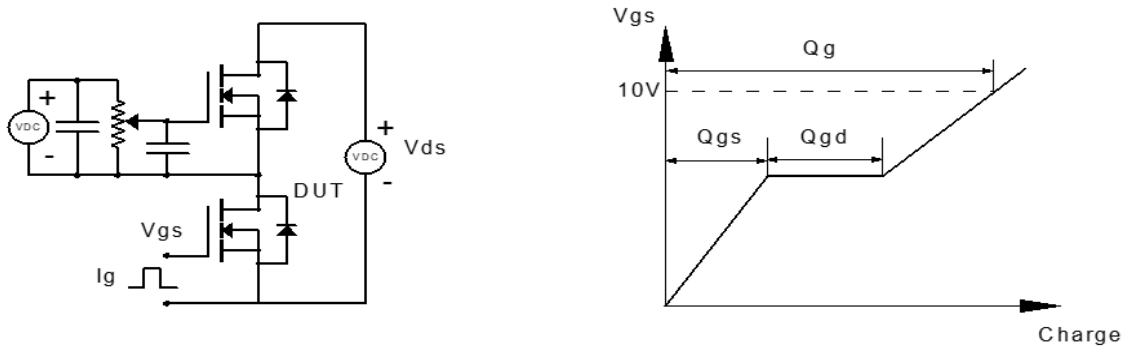


Figure 1: Gate Charge Test Circuit & Waveform

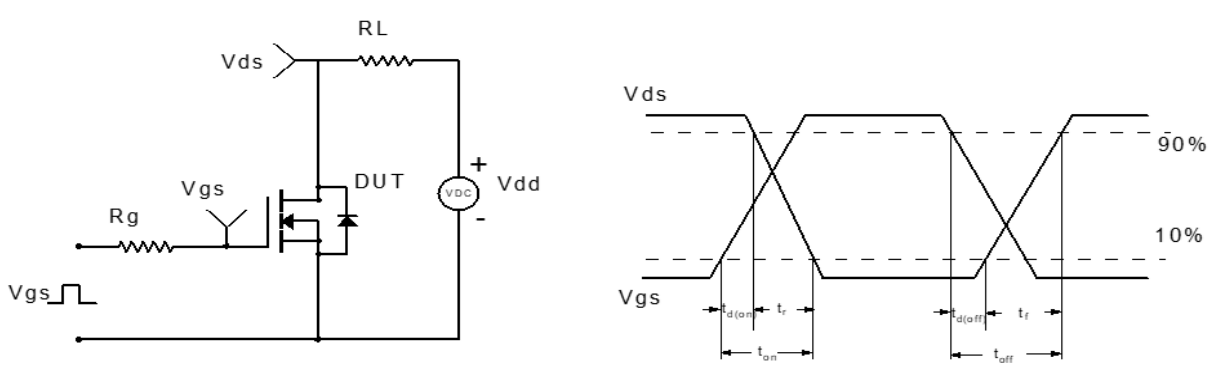


Figure 2: Resistive Switching Test Circuit & Waveform

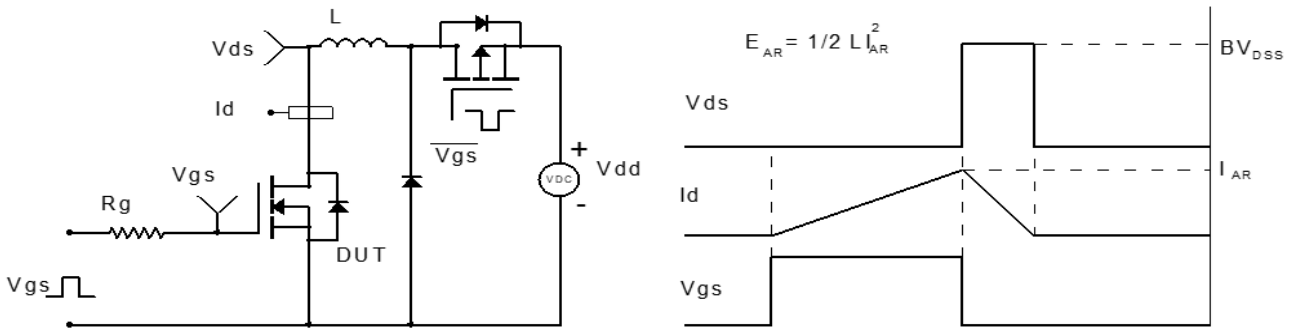


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

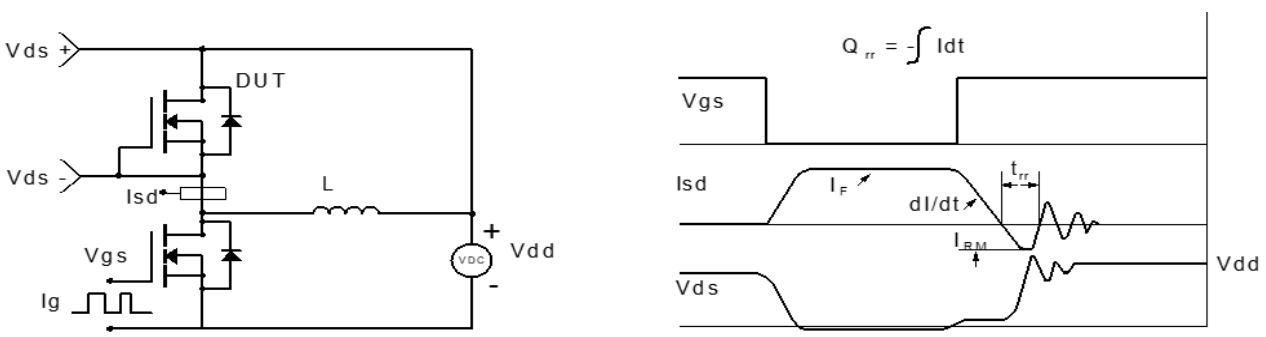


Figure 4: Diode Recovery Test Circuit & Waveform

Test Circuit

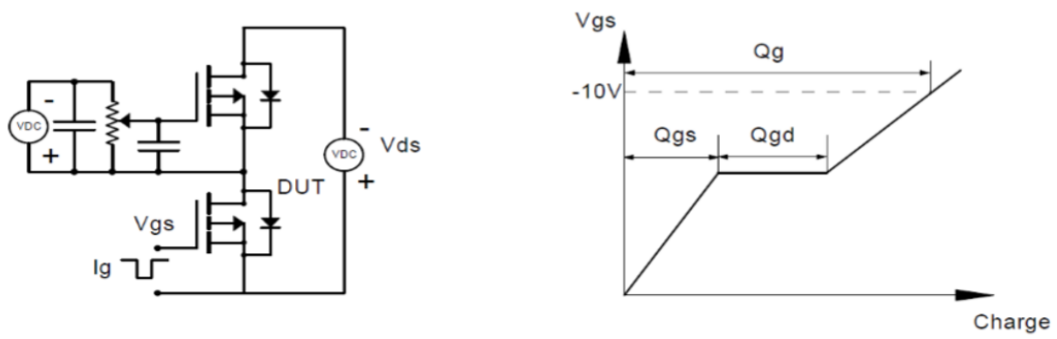


Figure 1: Gate Charge Test Circuit & Waveform

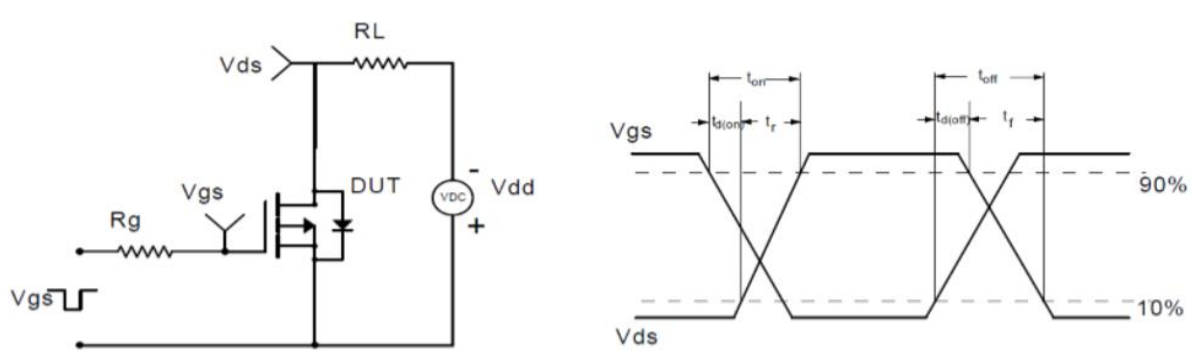


Figure 2: Resistive Switching Test Circuit & Waveform

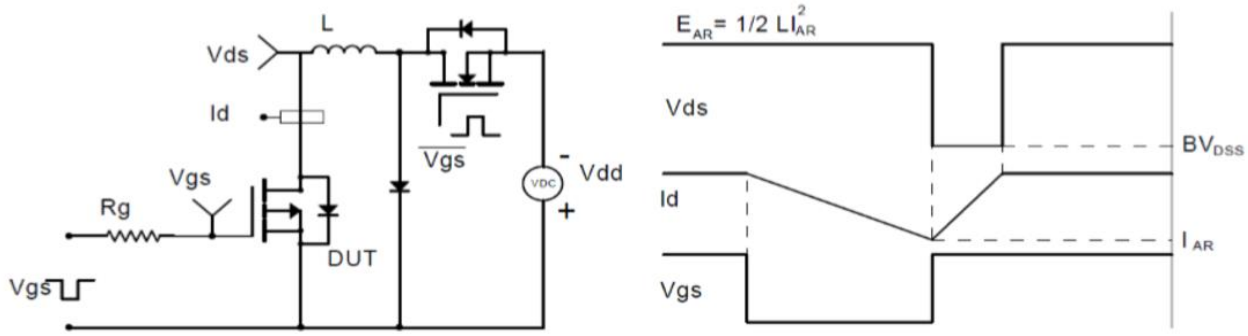


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

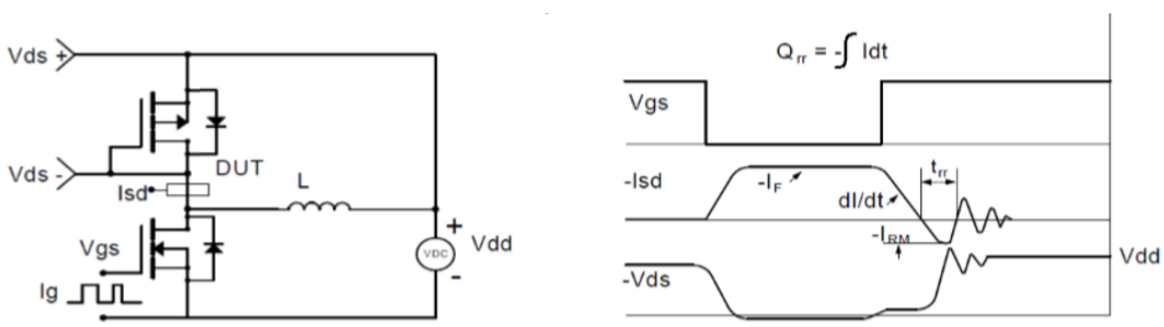
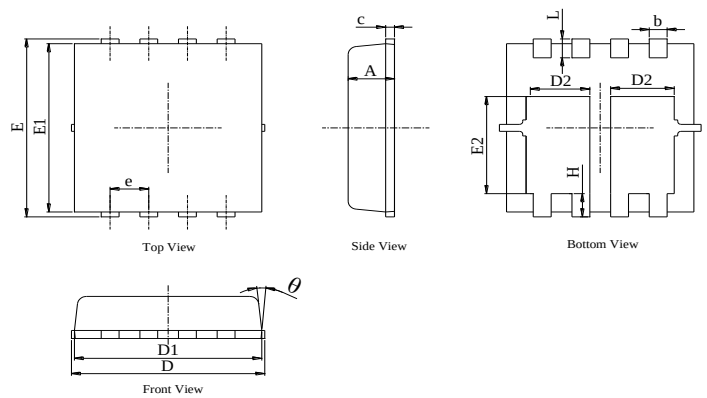


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5X6-8L-D)

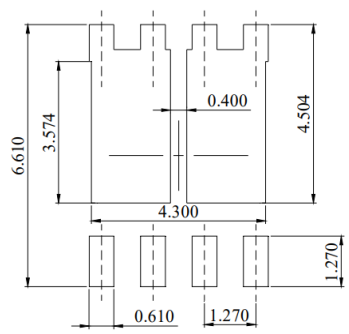
Package Outline



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. ALL DIMNESIONS IN MILLIMETER (ANNGLE IN DEGREE).
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLMETER		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.15
A1	0.00	–	0.10
b	0.31	0.41	0.51
b1	0.15	0.25	0.35
c	0.24	0.32	0.40
DIM	4.95	5.05	5.15
D1	4.00	4.10	4.20
D2	0.50	0.60	0.70
E	6.05	6.15	6.25
E1	5.50	5.60	5.70
E2	3.31	3.41	3.51
e	1.27BSC		
H	0.60	0.70	0.80
L	0.50	0.70	0.80
L1	–	–	0.13
a	–	–	12°

Recommended Soldering Footprint



DIMENSIONS:MILLIMETERS